

# MC10H123

## Triple 4-3-3-Input Bus Driver

### Description

The MC10H123 is a triple 4-3-3-Input Bus Driver.

The MC10H123 consists of three NOR gates designed for bus driving applications on card or between cards. Output low logic levels are specified with  $V_{OL} = -2.1$  Vdc so that the bus may be terminated to  $-2.0$  Vdc. The gate output, when low, appears as a high impedance to the bus, because the output emitter-followers of the MC10H123 are "turned-off." This eliminates discontinuities in the characteristic impedance of the bus.

The  $V_{OH}$  level is specified when driving a  $25\ \Omega$  load terminated to  $-2.0$  Vdc, the equivalent of a  $50\ \Omega$  bus terminated at both ends. Although  $25\ \Omega$  is the lowest characteristic impedance that can be driven by the MC10H123, higher impedance values may be used with this part. A typical  $50\ \Omega$  bus is shown in Figure 3.

### Features

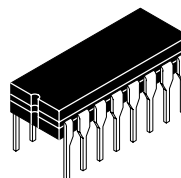
- Propagation Delay, 1.5 ns Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K™ Compatible
- Pb-Free Packages are Available\*



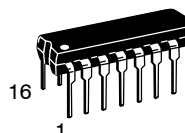
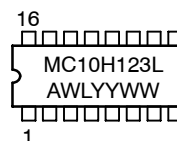
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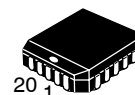
### MARKING DIAGRAMS\*



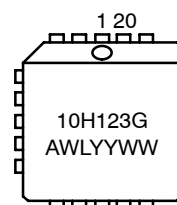
**CDIP-16**  
**L SUFFIX**  
**CASE 620A**



**PDIP-16**  
**P SUFFIX**  
**CASE 648**



**PLLC-20**  
**FN SUFFIX**  
**CASE 775**



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G = Pb-Free Package

\*For additional marking information, refer to Application Note AND8002/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

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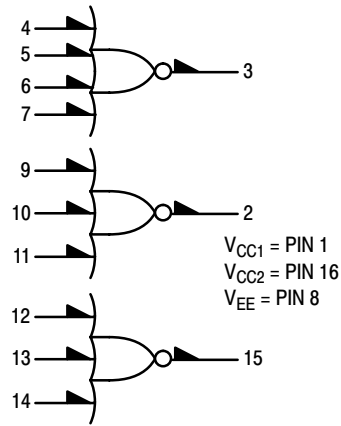
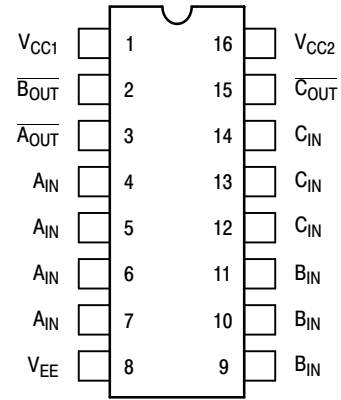


Figure 1. LOGIC DIAGRAM



Pin assignment is for Dual-in-Line Package.

Figure 2. Dip Pin Assignment

Table 1. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
$V_{EE}$	Power Supply ( $V_{CC} = 0$ )	-8.0 to 0	Vdc
$V_I$	Input Voltage ( $V_{CC} = 0$ )	0 to $V_{EE}$	Vdc
$I_{out}$	Output Current      Continuous Surge	50 100	mA
$T_A$	Operating Temperature Range	0 to +75	°C
$T_{stg}$	Storage Temperature Range   Plastic Ceramic	-55 to +150 -55 to +165	°C °C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS ( $V_{EE} = -5.2 \text{ V} \pm 5\%$ ) (Note 1)

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$I_E$	Power Supply Current		60		56		60	mA
$I_{inH}$	Input Current High		495		310		310	μA
$I_{inL}$	Input Current Low	0.5		0.5		0.3		μA
$V_{OH}$	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
$V_{OL}$	Low Output Voltage	-2.1	-2.03	-2.1	-2.03	-2.1	-2.03	Vdc
$V_{IH}$	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
$V_{IL}$	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

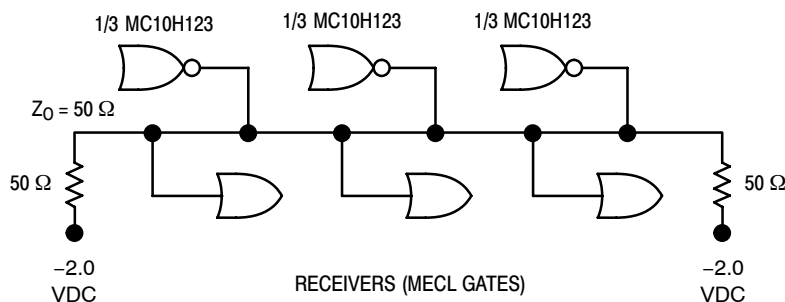
- Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50 Ω resistor to -2.1 V.

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**Table 3. AC CHARACTERISTICS**

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$t_{pd}$	Propagation Delay	0.7	1.5	0.7	1.6	0.7	1.7	ns
$t_r$	Rise Time	0.7	1.6	0.7	1.7	0.7	1.8	ns
$t_f$	Fall Time	0.7	1.6	0.7	1.7	0.7	1.8	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.



**Figure 3. 50 Ω Bus Driver (25 Ω Load)**

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC10H123FN	PLLC-20	46 Units / Rail
MC10H123FNG	PLLC-20 (Pb-Free)	46 Units / Rail
MC10H123FNR2	PLLC-20	500 / Tape & Reel
MC10H123FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel
MC10H123L	CDIP-16	25 Unit / Rail
MC10H123P	PDIP-16	25 Unit / Rail
MC10H123PG	PDIP-16 (Pb-Free)	25 Unit / Rail

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## PACKAGE DIMENSIONS

20 LEAD PLLC  
CASE 775-02  
ISSUE E



### NOTES:

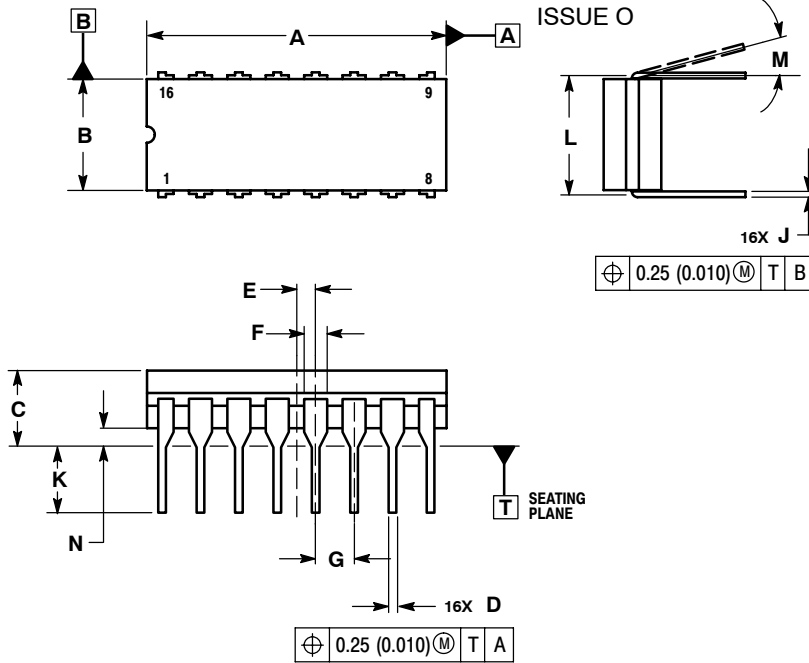
- DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- DIMENSIONS IN INCHES.
- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULD EXIT PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

# MC10H123

## PACKAGE DIMENSIONS

### CDIP-16 L SUFFIX CERAMIC DIP PACKAGE CASE 620A-01 ISSUE O

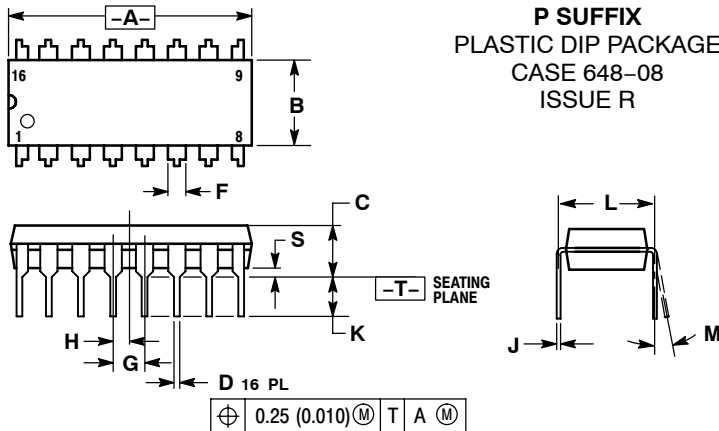


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
5. THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620-10.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	---	0.200	---	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

### PDIP-16 P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R




#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

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